

Service Manual

Telephone Equipment

Model No. KX-TG6411BX

KX-TG6412BX

KX-TG6413BX

KX-TGA641BX

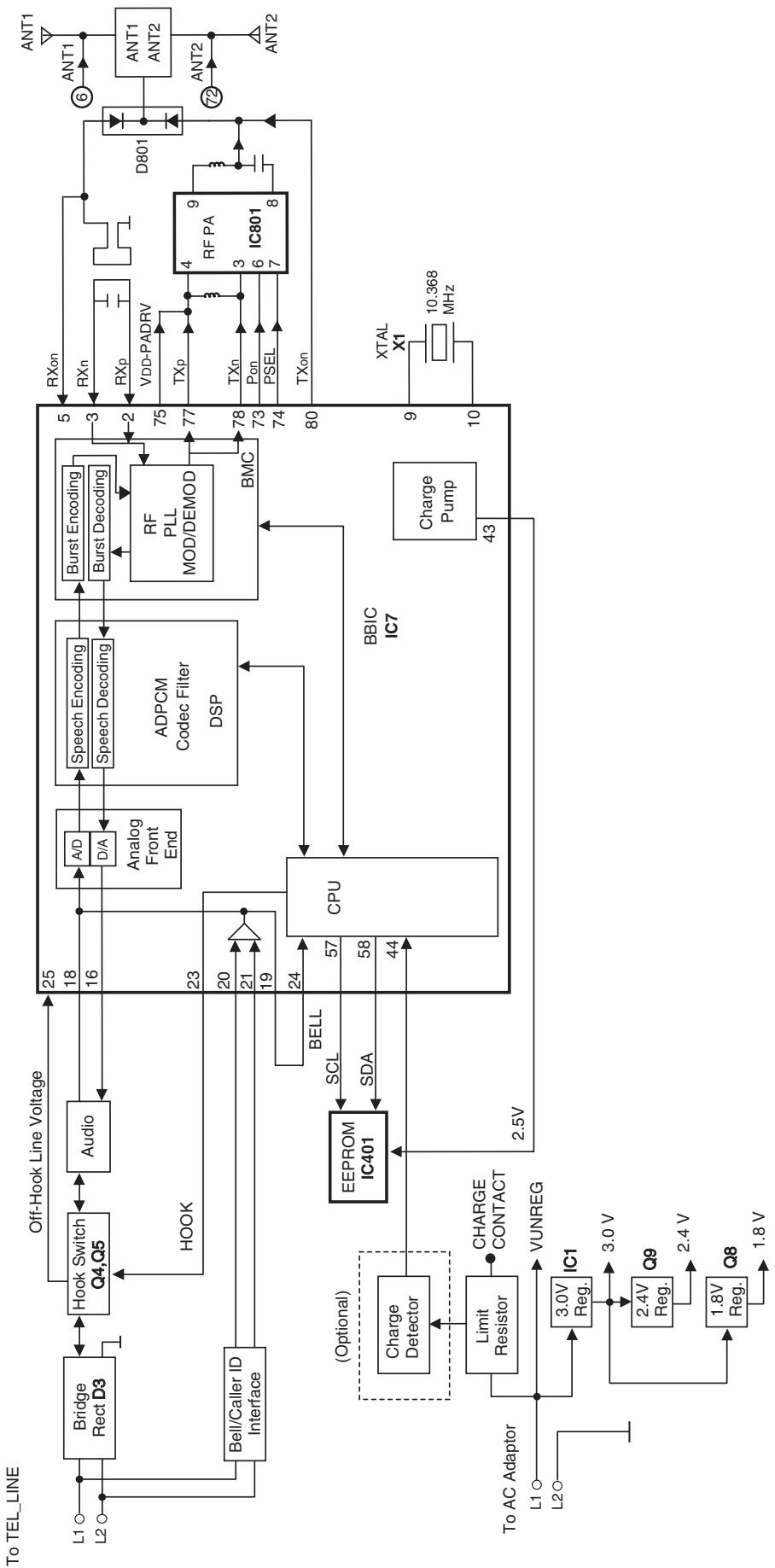
(for Asia, Middle Near East and other areas)

Panasonic

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1 Technical Descriptions

1.1. Block Diagram (Base Unit)



1.2. Circuit Operation (Base Unit)

1.2.1. Outline

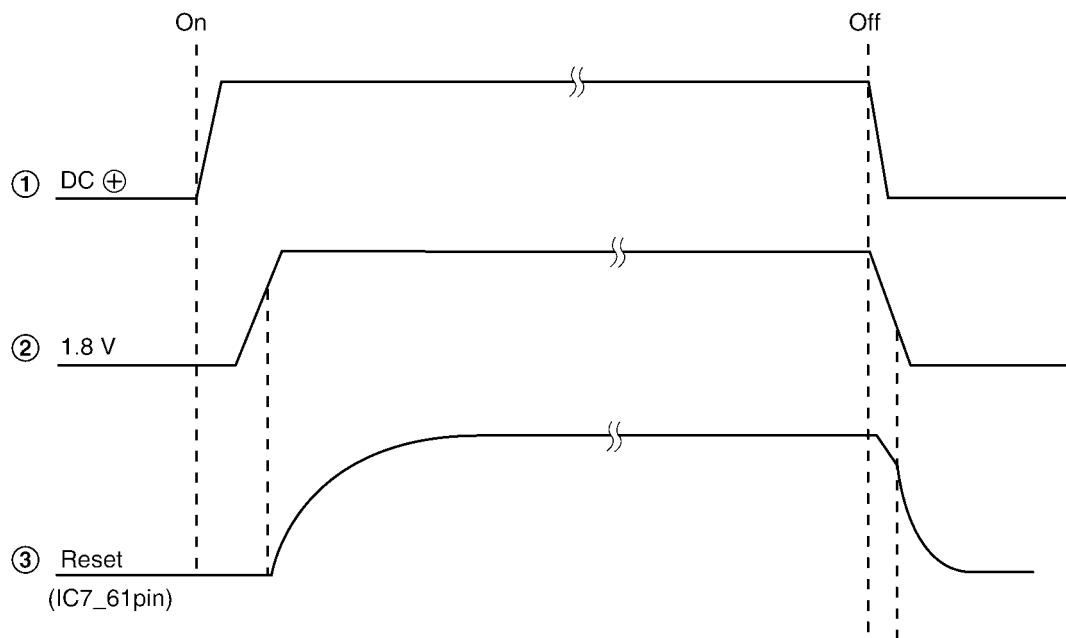
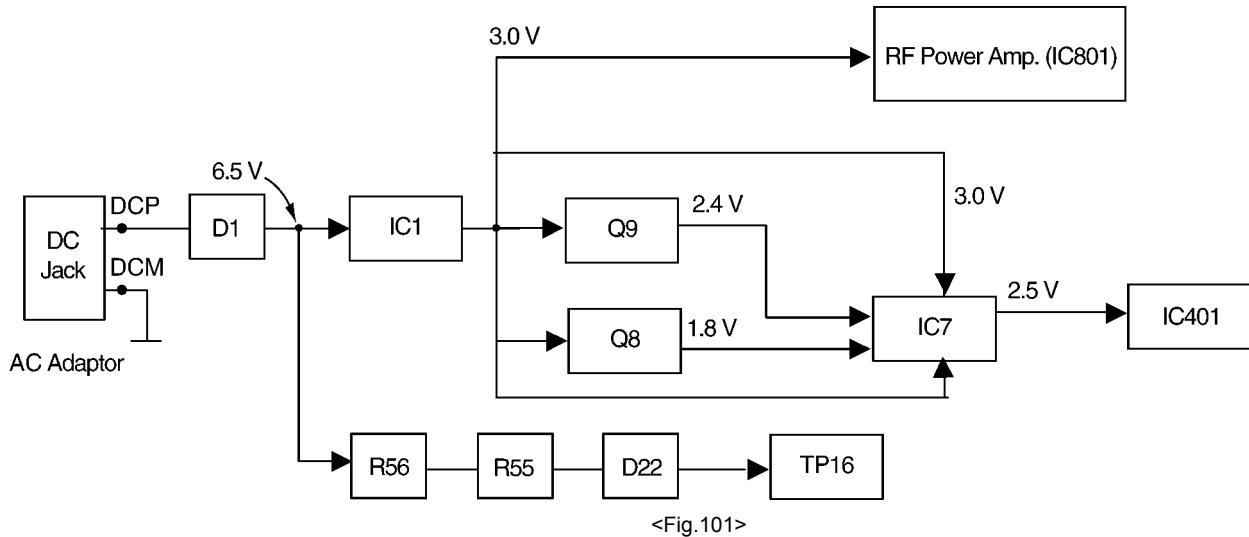
Base Unit consists of the following ICs as shown in **Block Diagram (Base Unit)** (P.2).

- DECT BBIC (Base Band IC): IC7
 - Handling all the audio, signal and data processing needed in a DECT base unit
 - Controlling the DECT specific physical layer and radio section (**Burst Module Controller section**)
 - ADPCM code filter for speech encoding and speech decoding (DSP section)
 - Echo-cancellation and Echo-suppression (DSP section)
 - Any tones (tone, sidetone, ringing tone, etc.) generation (DSP section)
 - DTMF receiver (DSP section)
 - Clock Generation for RF Module
 - ADC, DAC, timer, and power control circuitry
 - PLL Oscillator
 - Detector
 - Compress/Expander
 - First Mixer
 - All interfaces (ex: RF Power Amp, EEPROM, LED, Analog Front End, etc.)
- RF Power Amp.: IC801
 - Amplifier for transmission and reception
- EEPROM: IC401
 - Temporary operating parameters (for RF, etc.)
- Additionally,
 - Power Supply Circuit (+3.0 V, +2.4 V, +1.8 V output)
 - Crystal Circuit (10.368 MHz)
 - Charge Circuit
 - Telephone Line Interface Circuit

1.2.2. Power Supply Circuit

The power is supplied to the DECT BBIC, RF Module, EEPROM and Charge Contact from AC Adaptor (+6.5 V) as shown in Fig.101. The power supply is as follows;

- DECT BBIC (IC7):
 - DC Jack (+6.5 V) → D1 → IC1 → IC7
 - DC Jack (+6.5 V) → D1 → IC1 → Q9 → IC7
 - DC Jack (+6.5 V) → D1 → IC1 → Q8 → IC7
- RF Power Amp. (IC801):
 - DC Jack (+6.5 V) → D1 → IC1 → IC801 (Power AMP)
- EEPROM (IC401):
 - DC Jack (+6.5 V) → D1 → IC1 → IC7 → IC401
- Charge Contact (TP16):
 - DC Jack (+6.5 V) → D1 → R56 → R55 → D22 → TP16



1.2.3. Telephone Line Interface

<Function>

- Bell signal detection
- Clip signal detection
- ON/OFF hook circuit

Bell & Clip (: Calling Line Identification Presentation: Caller ID) signal detection:

In the standby mode, Q3 is open to cut the DC loop current and decrease the ring load.

When ring voltage appears at the L1T (A) and L1R (B) leads (when the telephone rings), the AC ring voltage is transferred as follows;

- B → L2 → C4 → R6 → R33 → IC7 Pin 21 (CID INp)
- A → L1 → C3 → R4 → R35 → IC7 Pin 20 (CID INn)

ON/OFF hook circuit:

In the standby mode, Q3 is open, and connected as to cut the DC loop current and to cut the voice signal. The unit is consequently in an **on-hook condition**.

When IC7 detects a ring signal or press the TALK Key onto the handset, Q4 turns on and then Q3 turns on, thus providing an **off-hook condition** (DC current flows through the circuit) and the following signal flow makes the loop current.

- B → L2 → D3 → Q3 → Q5 → R21 → R22 → D3 → L1 → A [OFF HOOK]

1.2.4. Transmitter/Receiver

- Audio Circuits and DTMF tone signal circuits.

Base Unit and Handset mainly consist of RF Module and DECT BBIC.

Base Unit and Handset transmit/receive voice signal and data signal through the antenna on carrier frequency.

1.2.4.1. Transmitter Block

The voice signal input from the TEL LINE interface goes to RF Power Amp. (IC801) through DECT BBIC (IC7) as shown in **Block Diagram (Base Unit)** (P.2)

The voice signal passes through the analog part of IC7 where it is amplified and converted to a digital audio stream signal. The burst switch controller processes this stream performing encryption and scrambling, adding the various other fields to produce the GAP (Generic Access Profile) standard DECT frame, assigning to a time slot and channel etc.

In IC7, the carrier frequency is changing, and frequency modulated RF signal is generated. In IC801, RF signal is amplified, and radiated from antenna. Handset detects the voice signal or data signal in the circuit same as the following explanation of Receiver Block.

1.2.4.2. Receiver Block

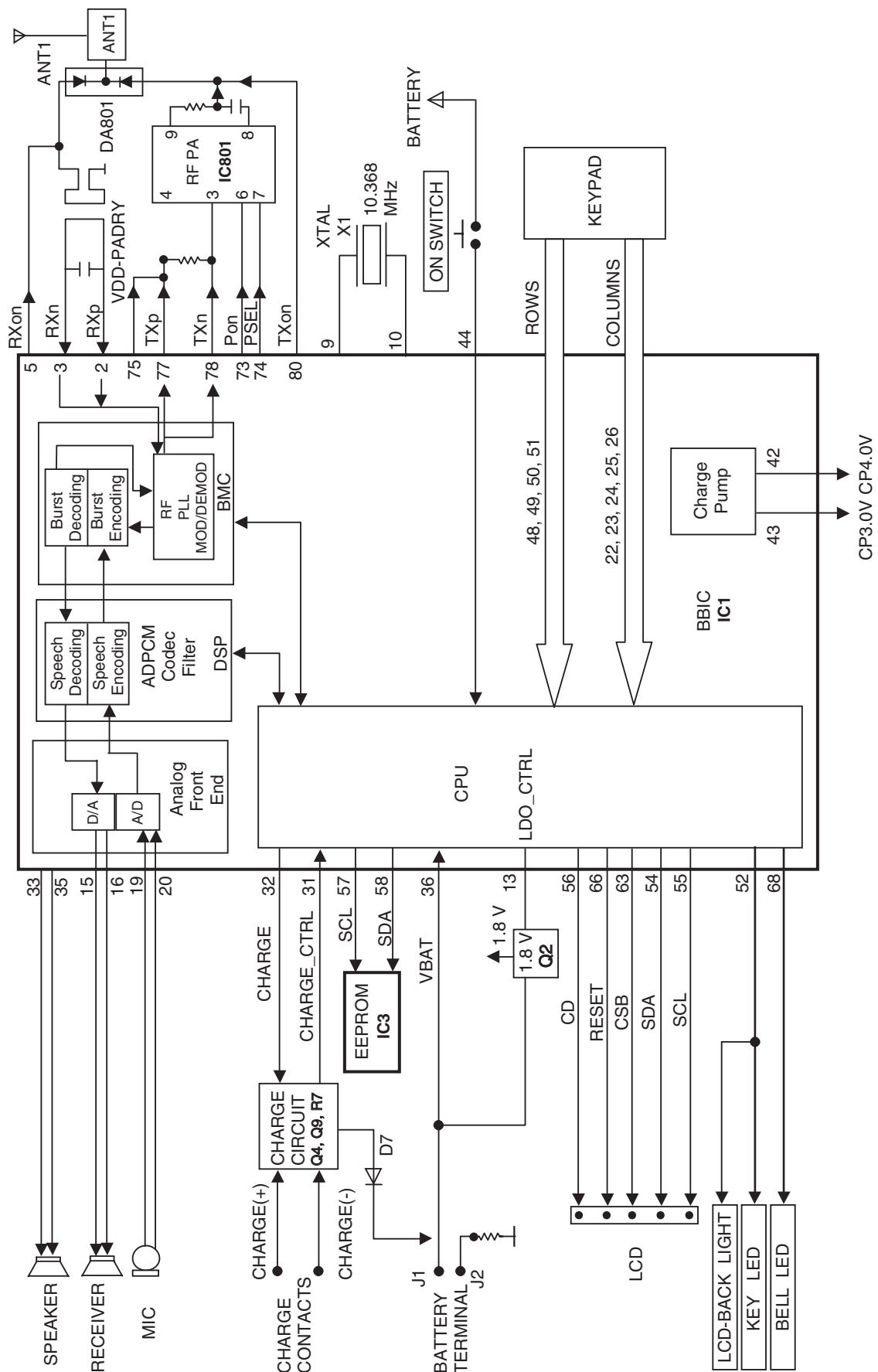
The signal of 1900 MHz band (1881.792 MHz ~ 1897.344 MHz) which is input from antenna is input to IC7 as shown in **Block Diagram (Base Unit)** (P.2).

In IC7, the signal of 1900 MHz band is downconverted to 864 kHz signal and demodulated, as GAP (Generic Access Profile) standard DECT frames. It passes through the decoding section burst switch controller where it separates out the frame information and performs de-encryption and de-scrambling as required. It then goes to the DSP section where it is turned back into analog audio. This is amplified by the analog front end, and goes to the TEL LINE Interface.

1.2.5. Pulse Dialling

During pulse dialing the hookswitch (Q3, Q4) is used to generate the pulses using the HOOK control signal, which is set high during pulses. To force the line impedance low during the "pause" intervals between dial pulses, the PULSE_DIAL signal turns on Q2.

1.3. Block Diagram (Handset)



1.4. Circuit Operation (Handset)

1.4.1. Outline

Handset consists of the following ICs as shown in **Block Diagram (Handset)** (P.6).

- DECT BBIC (Base Band IC): IC1
 - All data signals (forming/analyzing ACK or CMD signal)
 - All interfaces (ex: Key, Detector Circuit, Charge, DC/DC Converter, EEPROM, LCD, RF Power Amp.)
 - PLL Oscillator
 - Detector
 - Compress/Expander
 - Reception
- RF Power Amp: IC801
 - Amplifier for transmission
- EEPROM: IC3
 - Temporary operating parameters (for RF, etc.)

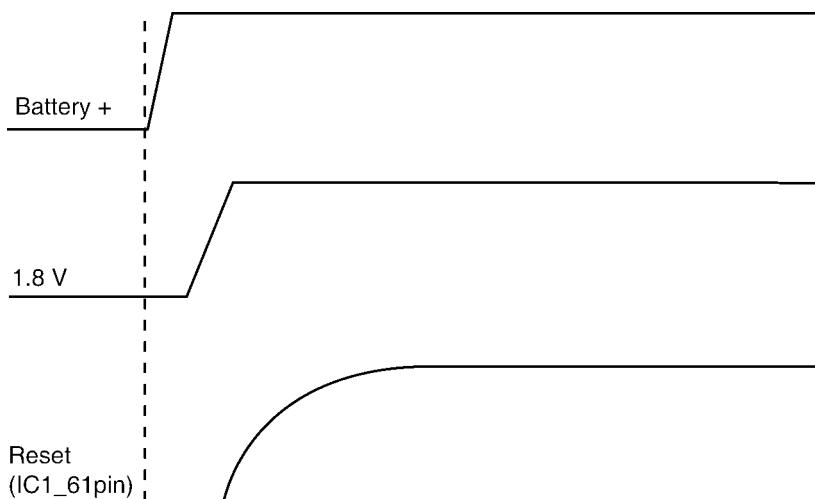
1.4.2. Power Supply Circuit/Reset Circuit

Circuit Operation:

When power on the Handset, the voltage is as follows;

BATTERY(2.2 V ~ 2.6 V: BATT+) → F1 → Q2 (1.8 V), IC1-43pin (2.5V)

The Reset signal generates IC1 (61 pin) and 1.8 V.



1.4.3. Charge Circuit

Circuit Operation:

When charging the handset on the Base Unit, the charge current is as follows;

DC+(6.5 V) → D1 → R56 → R55 → D22 → CHARGE+(Base) → CHARGE+(Handset) → Q4 → D7 → F1 → BATTERY+... Battery...

BATTERY- → R45 → GND → CHARGE-(Handset) → CHARGE-(Base) → GND → DC-(GND)

In this way, the BBIC on Handset detects the fact that the battery is charged.

The charge current is controlled by switching Q9 of Handset.

Refer to Fig.101 in **Power Supply Circuit** (P.4).

1.4.4. Battery Low/Power Down Detector

Circuit Operation:

“Battery Low” and “Power Down” are detected by BBIC which check the voltage from battery.

The detected voltage is as follows;

- Battery Low

Battery voltage: $V(Batt) \leq 2.25 V \pm 50 mV$

The BBIC detects this level and "█" starts flashing.

- Power Down

Battery voltage: $V(Batt) \leq 2.0 V \pm 50 mV$

The BBIC detects this level and power down.

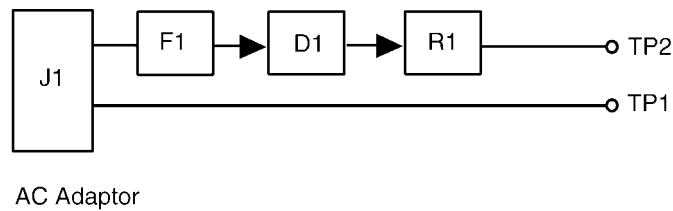
1.4.5. Speakerphone

The hands-free loudspeaker at SP+ and SP- is used to generate the ring alarm.

1.5. Circuit Operation (Charger Unit)

1.5.1. Power Supply Circuit

The power supply is as shown.



AC Adaptor

2 Schematic Diagram

2.1. For Schematic Diagram

2.1.1. Base Unit (Schematic Diagram (Base Unit))

Notes:

1. DC voltage measurements are taken with voltmeter from the negative voltage line.

Important Safety Notice:

Components identified by \triangle mark have special characteristics important for safety. When replacing any of these components, use only the manufacturer's specified parts.

2. The schematic diagrams may be modified at any time with the development of new technology.

2.1.2. Handset (Schematic Diagram (Handset))

Notes:

1. DC voltage measurements are taken with an oscilloscope or a tester with a ground.
2. The schematic diagram may be modified at any time with the development of new technology.

2.1.3. Charger Unit (Schematic Diagram (Charger Unit))

Notes:

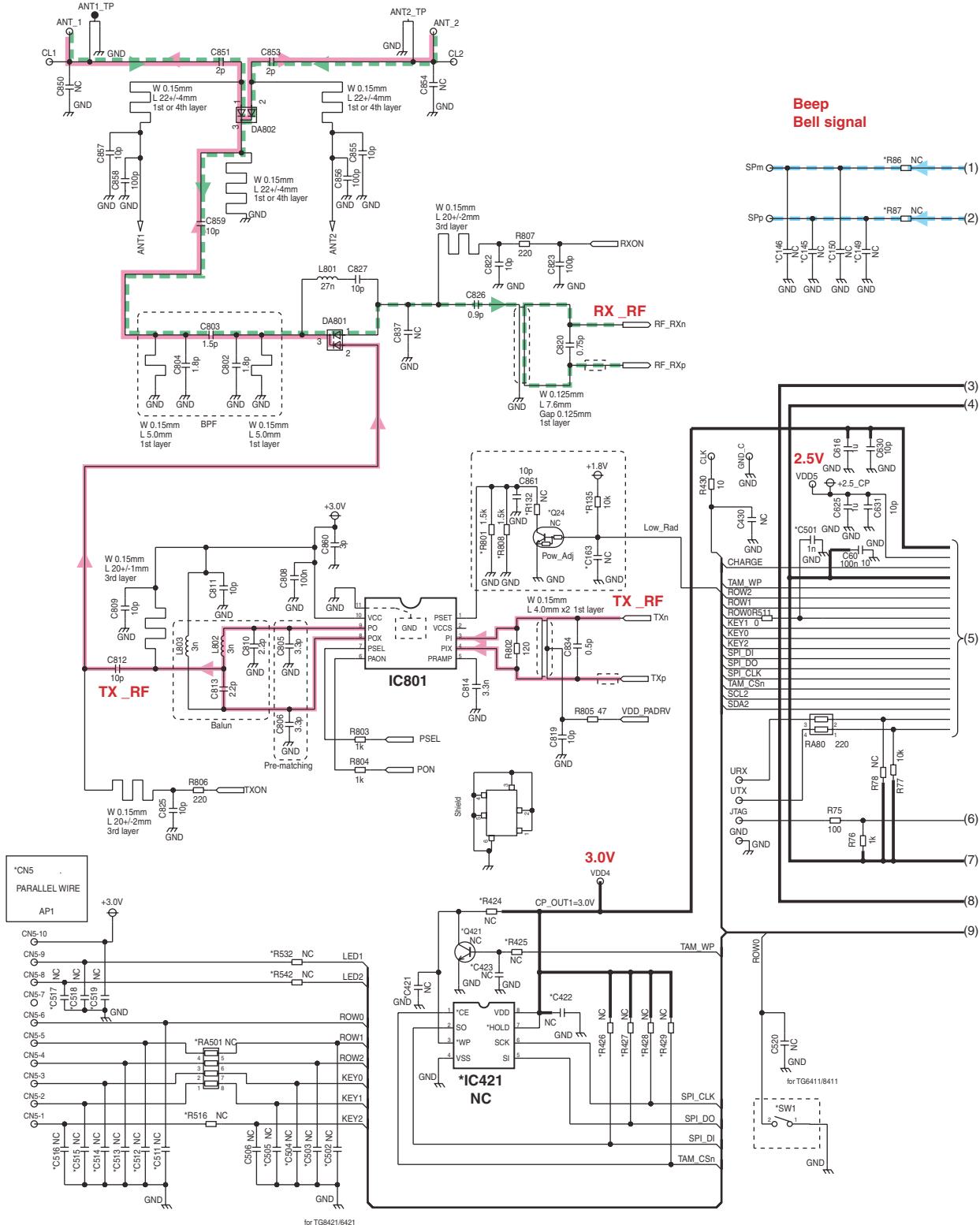
1. DC voltage measurements are taken with voltmeter from the negative voltage line.

Important Safety Notice:

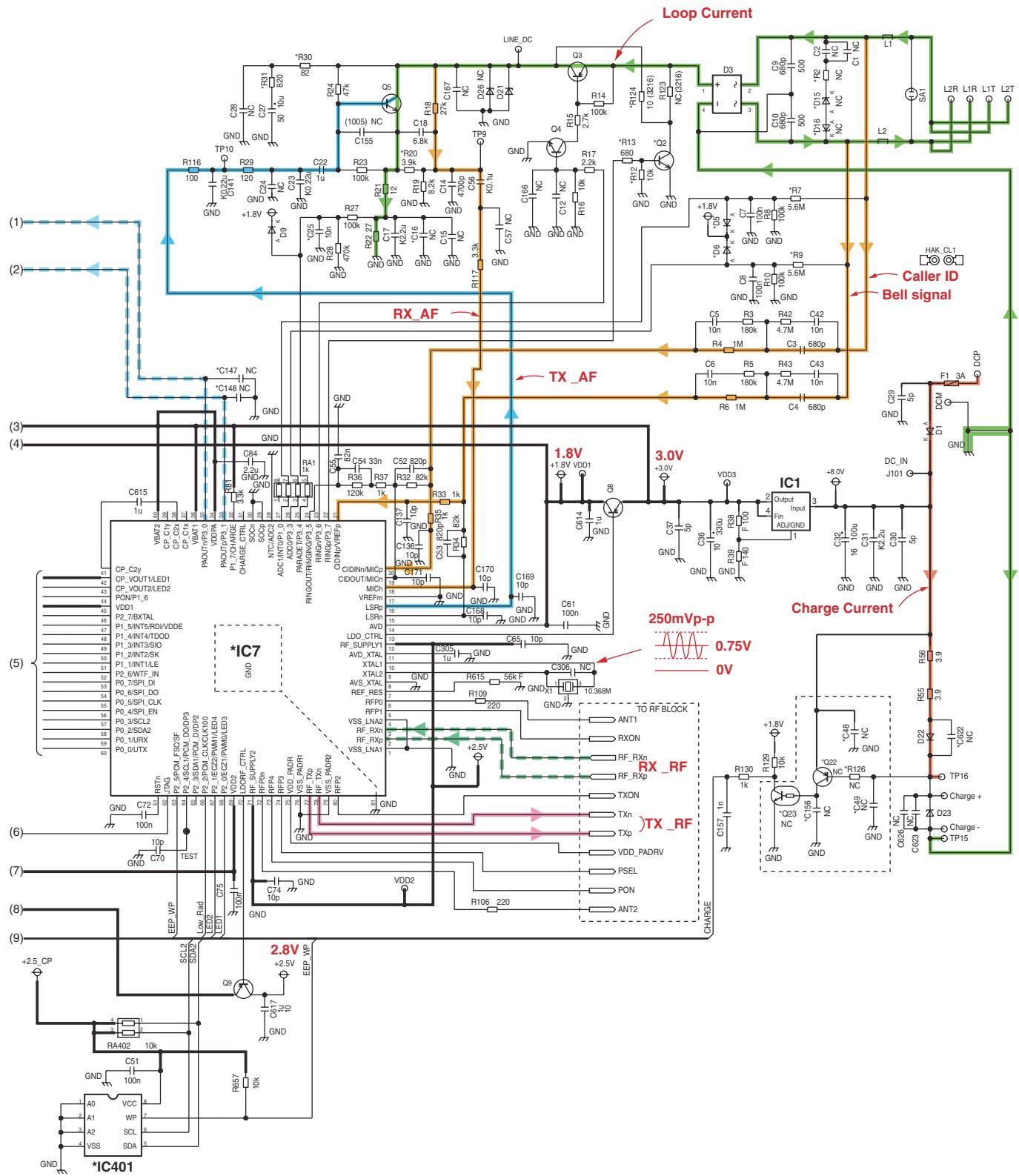
Components identified by \triangle mark have special characteristics important for safety. When replacing any of these components, use only the manufacturer's specified parts.

2. The schematic diagram may be modified at any time with the development of new technology.

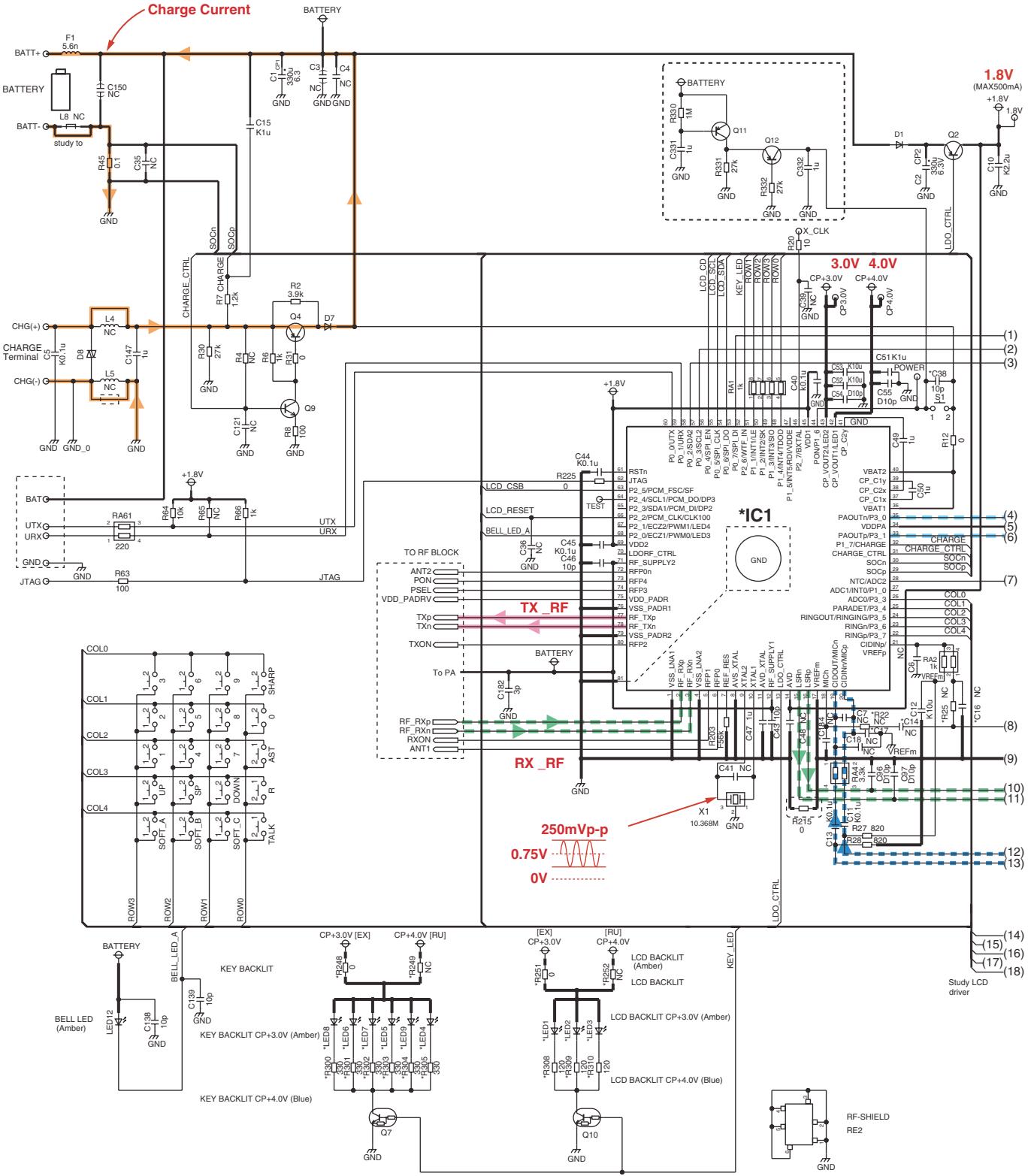
2.2. Schematic Diagram (Base Unit)



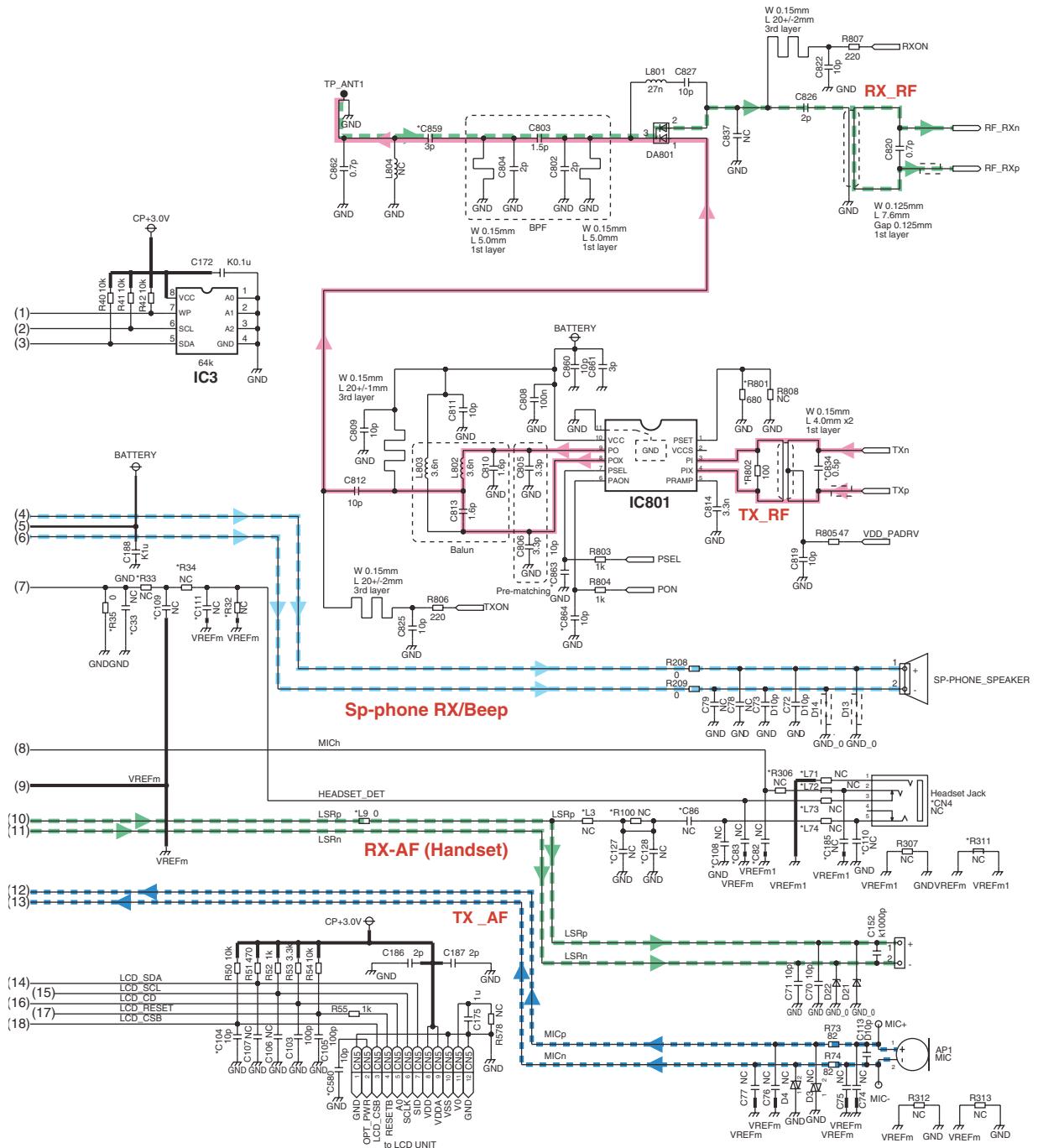
NC: No Components



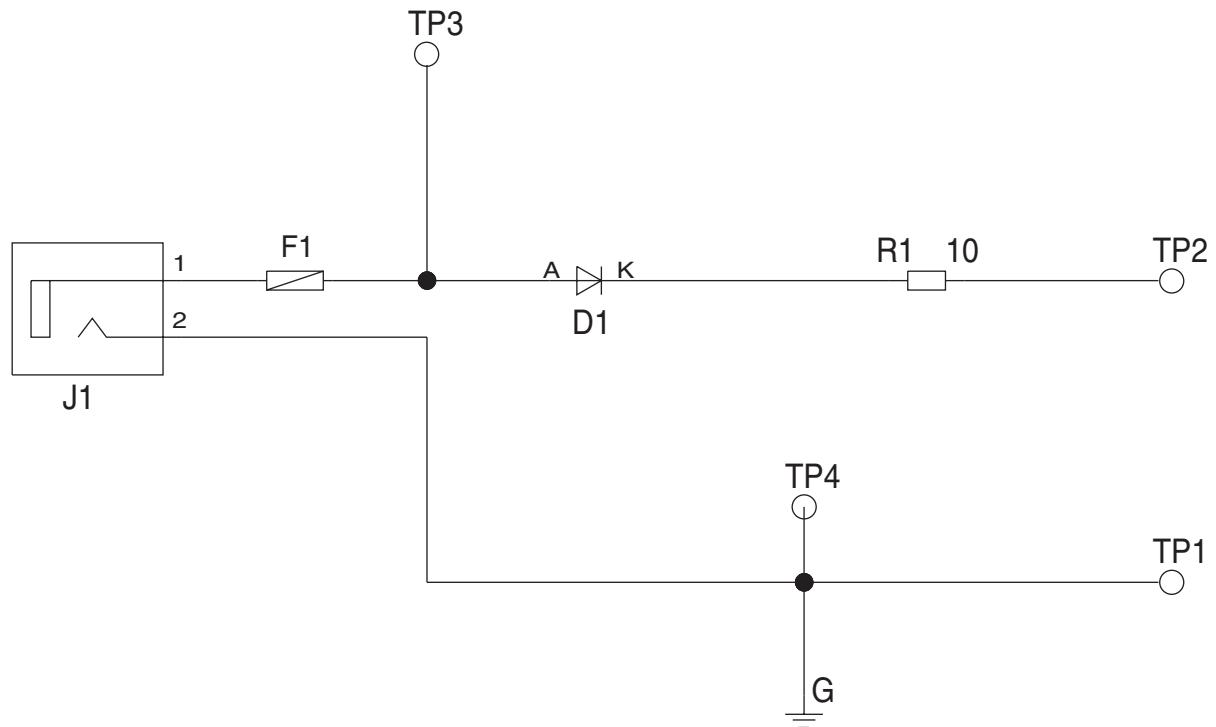
2.3. Schematic Diagram (Handset)



NC: No Components



2.4. Schematic Diagram (Charger Unit)

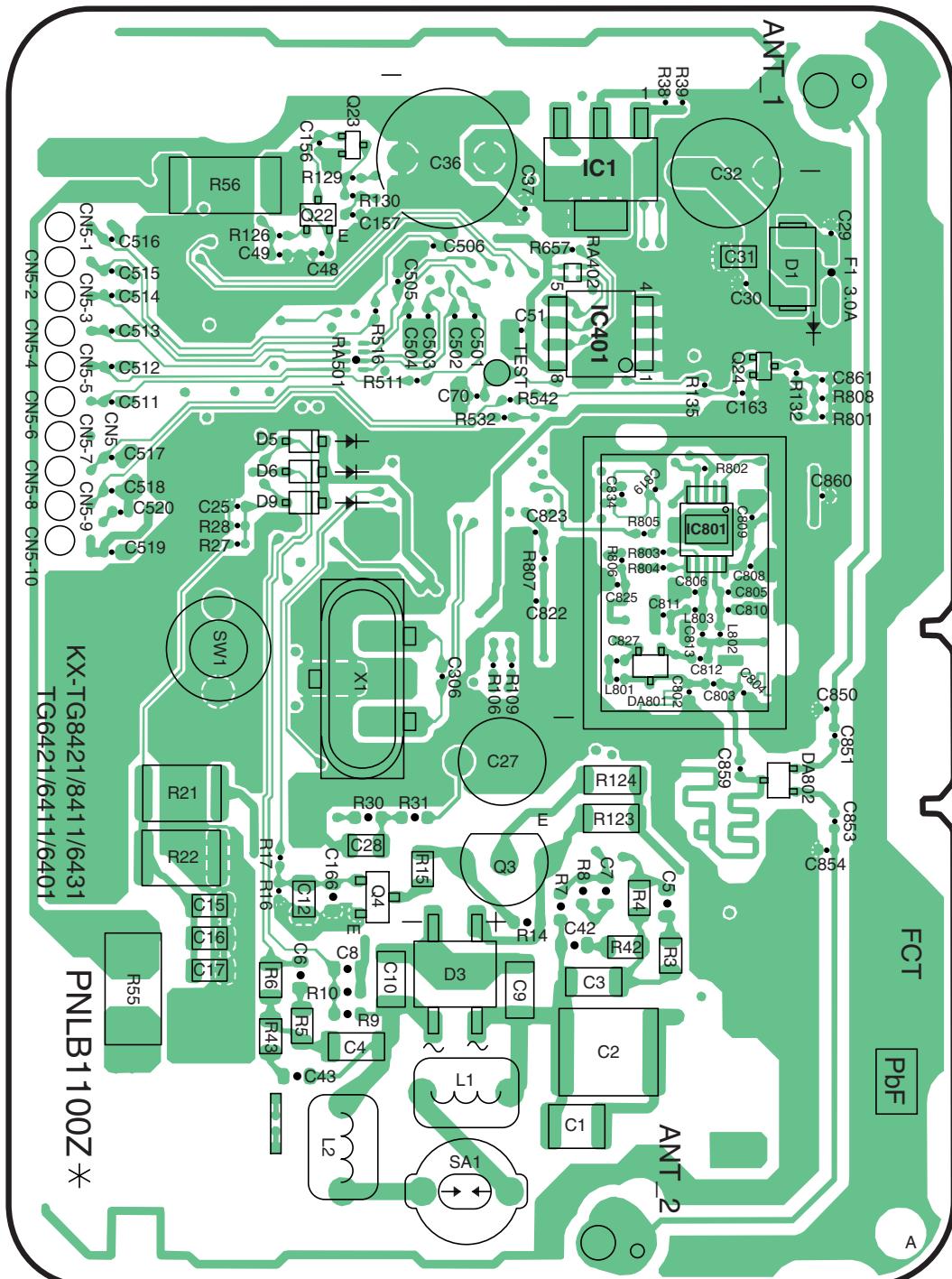


SCHEMATIC DIAGRAM (Charger Unit)

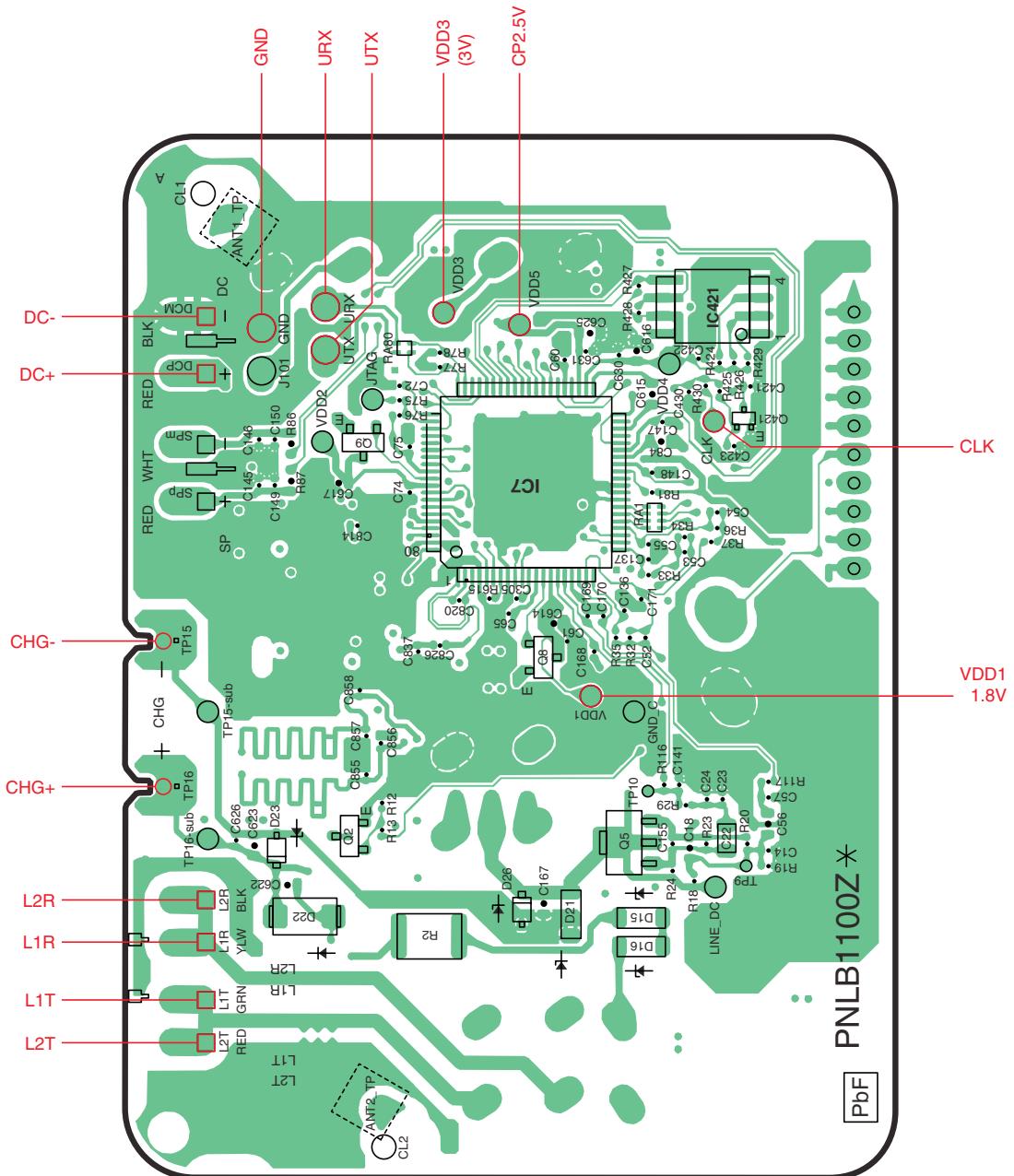
3 Printed Circuit Board

3.1. Circuit Board (Base Unit_MAIN)

3.1.1. Component View

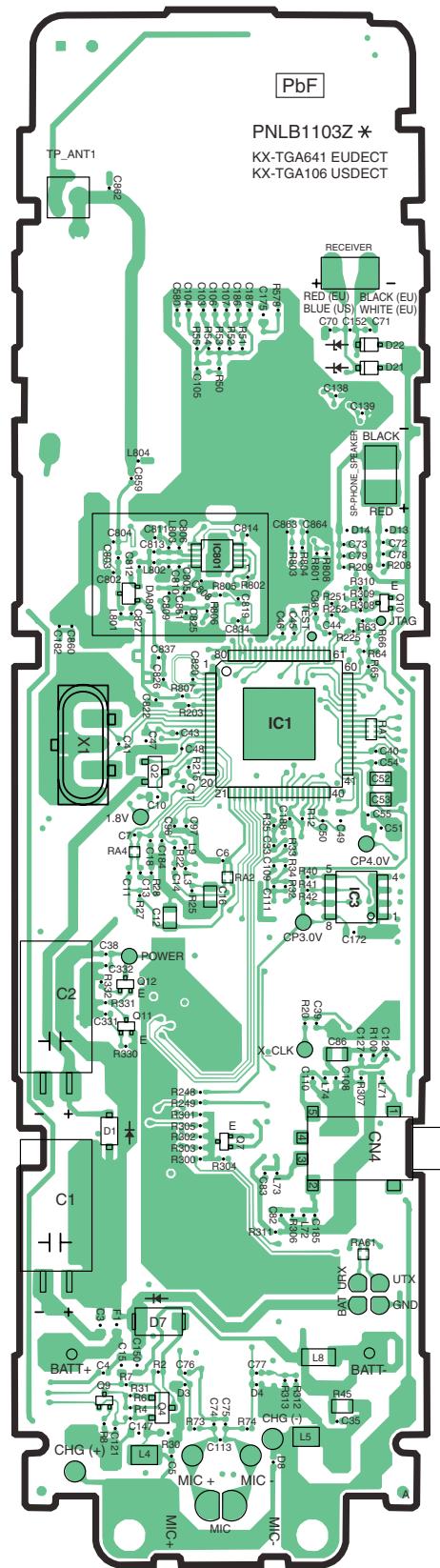


3.1.2. Bottom View

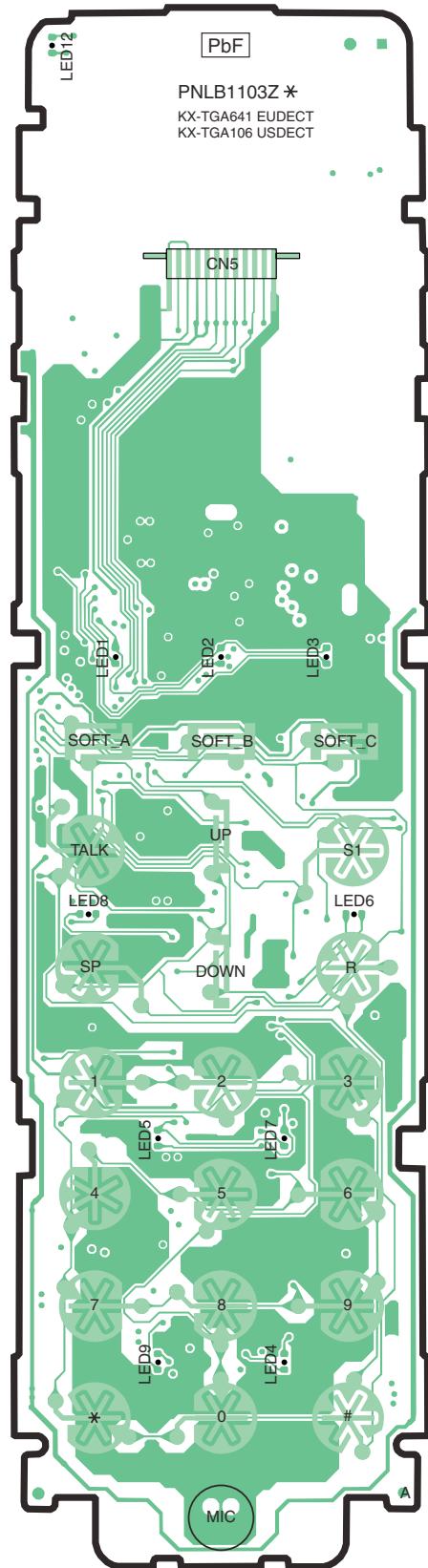


3.2. Circuit Board (Handset)

3.2.1. Component View

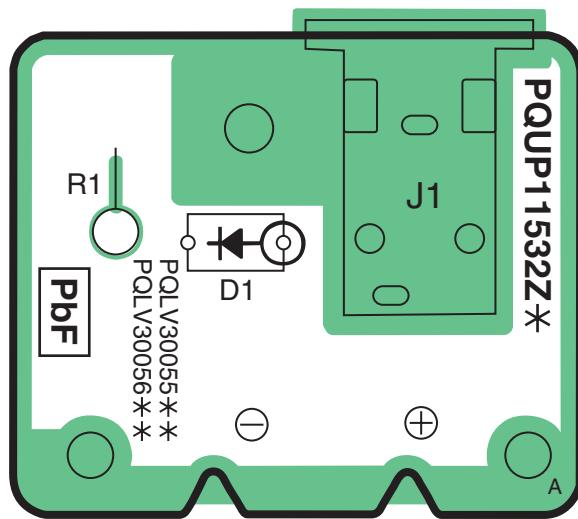


3.2.2. Bottom View



3.3. Circuit Board (Charger Unit)

3.3.1. Component View



3.3.2. Bottom View

